

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
TETSUSHI TAGUCHI	06/15/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	NATIONAL INSTITUTE FOR MATERIALS SCIENCE
<b>Street Address:</b>	2-1, SENGEN 1-CHOME
<b>City:</b>	TSUKUBA-SHI, IBARAKI
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	3050047
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	16071625
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<b>SIGNATURE:</b>	/T. Chyau Liang/
<b>DATE SIGNED:</b>	07/20/2018
<b>Total Attachments: 2</b>	
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source=Hirose-001-assignment#page2.tif	

## **ASSIGNMENT – WORLDWIDE**

For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the undersigned individual(s) (referred to herein as the "INVENTOR(S)") hereby assign, transfer, and set over to:

### **NATIONAL INSTITUTE FOR MATERIALS SCIENCE**

having the following address:

**2-1, Sengen 1-chome, Tsukuba-shi, Ibaraki 3050047  
JAPAN**

(referred to herein as "COMPANY"), its successors, and assigns, the entire right (including rights to claim priorities), title, and interest, worldwide, in and to the invention known by the following title:

### **SURGICAL SEALANT**

for which the undersigned has/have executed an application for patent in the United States of America, together with said patent application, all divisions, continuations, continuations-in-part, reissues, and extensions thereof, and all Letters Patent (domestic and foreign) which may be granted therefor. Such interest represents the entire ownership of said applications and Letters Patent when granted and is to be owned by COMPANY, its successors, and assigns, or their legal representatives, for the full and entire term for which such Letters Patent may be granted or extended, as fully and entirely as the same would have been enjoyed by the INVENTOR(S) if this assignment had not been made.

In addition, the undersigned INVENTOR(S) each hereby agrees:

1. To sign and execute any further documents which may be necessary or desirable, lawful, and proper in connection with the prosecution of all applications for patent(s) on the INVENTION in the United States, including without limitation said application and all divisions, continuations, continuations-in-part, amendments thereof, and all interference proceedings associated therewith, or otherwise necessary or desirable to secure the title thereto to COMPANY;
2. To execute all papers and documents and to perform all lawful acts which may be necessary in connection with claims to priority or otherwise under the International Convention for the Protection of Industrial Property or similar treaties or agreements;
3. To perform all lawful affirmative acts which may be necessary to obtain the grant of a valid and enforceable patent to COMPANY.

The undersigned INVENTOR(S) each hereby grants to the firm of LIANG LEGAL GROUP, PLLC the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for the recordation of this document.

IN WITNESS WHEREOF, this Assignment has been executed by each of the undersigned individuals on the date appearing by such individual's signature:

<u>June 15, 2018</u> Date	1 <sup>st</sup> Inventor Signature: <u>Tetsushi Taguchi</u> Print or Type Name: <u>Tetsushi TAGUCHI</u>
_____ Date	2 <sup>nd</sup> Inventor Signature: _____ Print or Type Name: _____
_____ Date	3 <sup>rd</sup> Inventor Signature: _____ Print or Type Name: _____
_____ Date	4 <sup>th</sup> Inventor Signature: _____ Print or Type Name: _____
_____ Date	5 <sup>th</sup> Inventor Signature: _____ Print or Type Name: _____

WITNESSES	_____ Date	Signature of Witness: _____ Print or Type Name: _____
	_____ Date	Signature of Witness: _____ Print or Type Name: _____

When this Assignment is not filed concurrently with the patent application, the following identifying information may be added after execution:

U.S. Application Serial No.: 16/071,625  
Filing Date: July 20, 2018